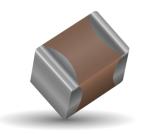
X7S Dielectric

General Specifications





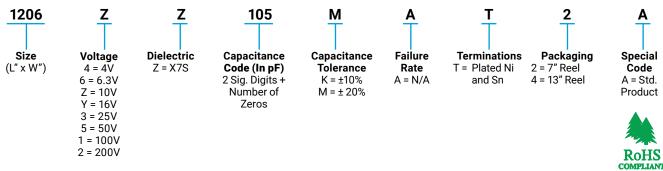
GENERAL DESCRIPTION

X7S formulations are called "temperature stable" ceramics and fall into EIA Class II materials. Its temperature variation of capacitance s within $\pm 22\%$ from -55° C to $\pm 125^{\circ}$ C. This capacitance change is non-linear.

Capacitance for X7S varies under the influence of electrical operating conditions such as voltage and frequency.

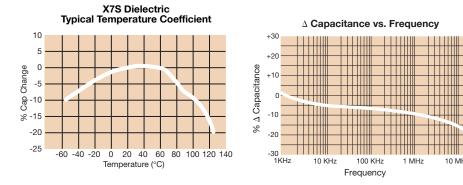
X7S dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

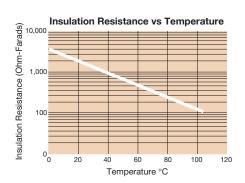
PART NUMBER (SEE PAGE 4 FOR COMPLETE PART NUMBER EXPLANATION)



NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers.

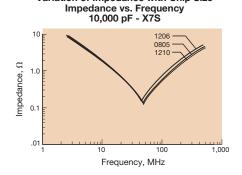
TYPICAL ELECTRICAL CHARACTERISTICS





Impedance vs. Frequency 1,000 pF vs. 10,000 pF - X7S 0805 10.00 pF 10,000 pF 10,000 pF

Variation of Impedance with Cap Value



Variation of Impedance with Chip Size

Variation of Impedance with Chip Size



X7S Dielectric

Specifications and Test Methods



Parameter/Test Operating Temperature Range		X7S Specification Limits	Measuring Conditions						
		-55°C to +125°C	Temperature C	ycle Chamber					
	on Factor	Within specified tolerance ≤ 5.0% for ≥ 100V DC rating ≤ 5.0% for ≥ 25V DC rating ≤ 10.0% for ≥ 10V DC rating ≤ 10.0% for ≤ 10V DC rating	Freq.: 1.0 k Voltage: 1.0 For Cap > 10 μF, 0	Vrms ± .2V					
Insulation	Resistance	100,000ΜΩ or 1000ΜΩ - μF, whichever is less	Charge device with 120 ± 5 secs @ roo						
Dielectric	Strength	No breakdown or visual defects	Charge device with 250 1-5 seconds, w/charge limited to 50	and discharge current					
	Appearance	No defects	Deflectio						
Resistance to	Capacitance Variation	≤ ±12%	Test Time: 30 seconds 1mm/sec						
Stresses	Dissipation Factor Insulation	Meets Initial Values (As Above)							
	Resistance	≥ Initial Value x 0.3	90 mm —						
Solder	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.9						
Flexure	Appearance	No defects, <25% leaching of either end terminal							
	Capacitance Variation	≤ ±7.5%							
	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.						
Insulation Resistance		Meets Initial Values (As Above)	nours before measuring electrical properties.						
Solder Heat	Dielectric Strength	Meets Initial Values (As Above)							
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes					
	Capacitance Variation	≤ ±7.5%	Step 2: Room Temp	≤ 3 minutes					
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes					
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes					
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles 24 ± 2 hours at ro						
	Appearance	No visual defects							
	Capacitance Variation	≤ ±12.5%	Charge device with 1.5 r test chamber set						
Load Life	Dissipation Factor	≤ Initial Value x 2.0 (See Above)	for 1000 hou						
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamb temperature for 24 ± 2 h						
	Dielectric Strength	Meets Initial Values (As Above)	-						
	Appearance	No visual defects							
	Capacitance Variation ≤ ±12.5%		temperature for 24 \pm 2 hours before measuring. Meets Initial Values (As Above) No visual defects $\leq \pm 12.5\%$ Store in a test chamber set at 85°C \pm 2°C/ 85% \pm 5% relative humidity for 1000 hours						
Load Humidity	Dissipation Factor	≤ Initial Value x 2.0 (See Above)							
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	per and stabilize at room and humidity for						
	Dielectric Strength	Meets Initial Values (As Above)	24 ± 2 hours bef	ore measuring.					



X7S Dielectric

Capacitance Range



PREFERRED SIZES ARE SHADED

				ш																	
SIZI	E	0402		0603		0805		1206		121	0										
Solder	ing	Reflow/Wav	е	Reflow/Wav	e Re	eflow/Wave	Re	flow/W	ave	Reflow	Only										
Packag	ging	All Paper		All Paper		er/Embossed		er/Embo		Paper/Em											
(L) Length	mm (in)	1.00 ±		1.60 ± 0.15		2.01 ± 0.20		.20 ± 0.2		3.20 ±											
	(in.) mm	(0.040 ± 0. 0.50 ±		0.063 ± 0.00 0.81 ± 0.15		079 ± 0.008) .25 ± 0.20		.60 ± 0.0		(0.126 ± 2.50 ±											
W) Width	(in.)	(0.020 ± 0.		$(0.032 \pm 0.00$		049 ± 0.008)		063 ± 0.0		(0.098 ±											
(t)	mm	0.25 ±		0.35 ± 0.15		0.50 ± 0.25		.50 ± 0.1		0.50 ±											
Terminal	(in.)	(0.010 ± 0.	.006)	(0.014 ± 0.00	6) (0.0	020 ± 0.010)		020 ± 0.0		(0.020 ±											
Сар	WVDC 100	6.3		6.3		4	10	50	100	6.3	3										
(pF)	150							ı	_	· 💉											
(I)	220									\sim	>										
	330						~		_	`) ') ÎT										
	470									1	1										
	680 1000						+		<u> </u>		_										
	1500								a t	7											
	2200								, ,	<u> </u>											
	3300																				
	4700											ĺ									
Сар	6800 0.010						+														
(μF)	0.015																				
(I)	0.022																				
	0.033	С																			
	0.047	С																			
	0.068	C C					+														
	0.10	C																			
	0.22																				
	0.33			G																	
	0.47			G																	
	0.68			G G			-														
	1.5			G		N															
	2.2					N															
	3.3					N															
	4.7					N	Q		Q*												
	10 22						+			Z											
	47																				
	100																				
	WVDC	6.3		6.3		4	10	50	100	6.3	3										
	SIZE	0402		0603		0805		1206		121	0										
Latter	Δ.		г	0		l v	14		N			_		Х У		V V	l v l v	V V 7	X Y Z	V V 7	V V 7
Letter	A 0.22	C	E 0.71	G	J	K 1.02	M	-	N 40	P 1.50	Q 1.00		X 200					 			
Max. Thickness	0.33 (0.013)	0.56 (0.022)	0.71 (0.028)	0.90 (0.035)	0.94 (0.037)	1.02 (0.040)	1.27 (0.050)		.40 055)	1.52 (0.060)	1.90 (0.075)		(0.090)								
7	(0.0.0)	· /	PAPER	(0.000)	(0.007)	(0.0.0)	(0.000)	, (0.	- 50,	· /	SSED		(0.050)	(0.050) (0.155)	(0.050) (0.125)	(0.050) (0.105)	(0.055) (0.155)	(0.033) (0.133)	(0.055) (0.055)	(0.055) (0.055)	(0.025) (0.155)

^{*}Contact Factory for Specifications

